- Qualification in Accordance With AEC-Q100†
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- ESD Protection Exceeds 1500 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Operating Range of 4.5 V to 5.5 V
- Max t<sub>pd</sub> of 7.5 ns at 5 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±8-mA Output Drive at 5 V
- Inputs Are TTL-Voltage Compatible

# NC 1 5 V<sub>CC</sub> A 2 GND 3 4 Y

NC - No internal connection

### description/ordering information

The SN74AHCT1G04 contains one gate. The device performs the Boolean function  $Y = \overline{A}$ .

### ORDERING INFORMATION

TA	PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	CAHCT1G04QDCKRQ1	BCS

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

### **FUNCTION TABLE**

	INPUT A	OUTPUT Y
Г	Н	L
l	L	Н

### logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>†</sup>Contact factory for details. Q100 qualification data available on request.

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Note 1)	0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{ K }(V_{ } < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	252°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-8	mA
lOL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-40	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Voc	T,	T <sub>A</sub> = 25°C		MIN MAX	MAX	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	IVIIIV	WAA	UNIT
Vou	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		V
VOH	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
Voi	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1	V
VOL	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.44	
IĮ	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1		10	μΑ
∆lcc <sup>‡</sup>	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		4	10		10	pF

<sup>‡</sup> This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or VCC.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

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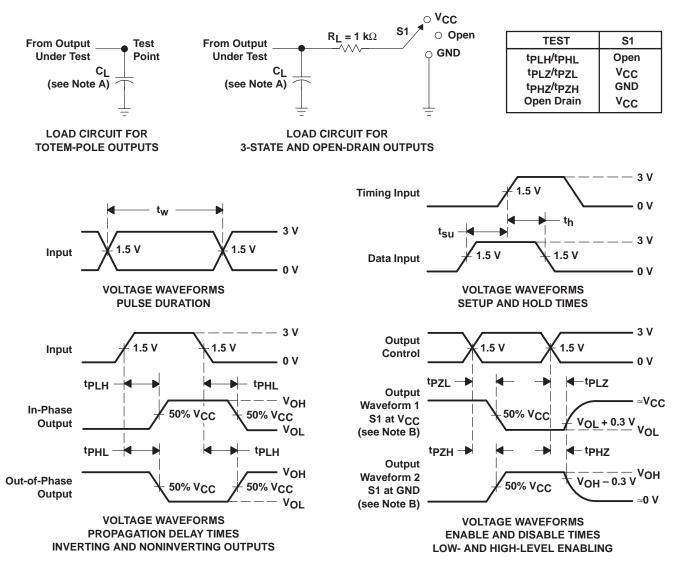
# switching characteristics over recommended operating free-air temperature range, $V_{CC}=5~V\pm0.5~V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	չ = 25°C	;	MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIN	WAX	ONIT
<sup>t</sup> PLH	Λ	V	C: -15 pF		4.7	6.7	1	7.5	no
<sup>t</sup> PHL	A	ī	$C_L = 15 pF$		4.7	6.7	1	7.5	ns
<sup>t</sup> PLH	Δ.	V	$C_{1} = 50  pF$		5.5	7.7	1	8.5	no
<sup>t</sup> PHL	A	ī	CL = 50 pr		5.5	7.7	1	8.5	ns

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER		ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	14	pF

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns.  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





### PACKAGE OPTION ADDENDUM

9-Nov-2006

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing		kage Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CAHCT1G04QDCKRQ1	ACTIVE	SC70	DCK	5 3	000	TBD	A42 SNPB	Level-1-235C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

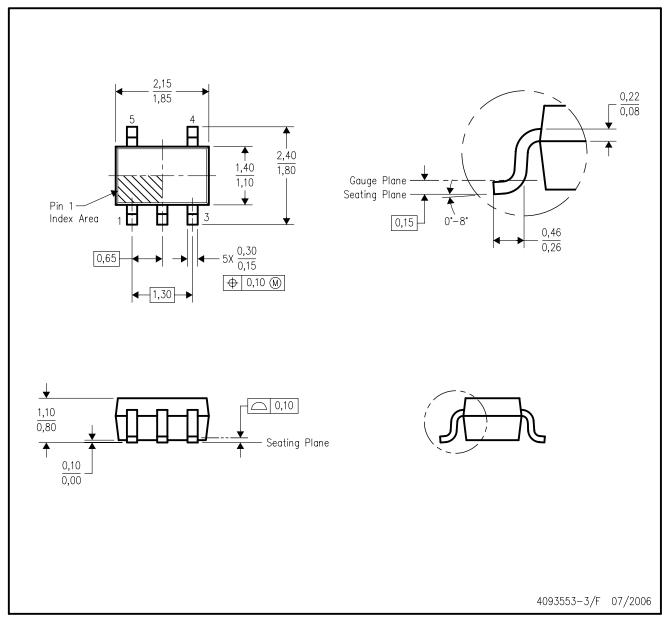
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# DCK (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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